

Upcoming: April 12–16 MRS Spring Meeting/ICEM 2004, MRS/IUMRS; May 16–19 Magneto-Optical Recording Intl. Symp. (MORIS 2004), Endorsed.

To list an event in the Calendar, contact **J. Meiksin, Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3004 ext. 522; fax 724-779-8313; bulletin@mrs.org.**

MRS, A-MRS, C-MRS, E-MRS, MRS-A, MRS-I, MRS-J, MRS-K, MRS-R, MRS-S, MRS-T, M-MRS, or IUMRS at the end of an entry indicates sponsorship or co-sponsorship of an event by the International Union of Materials Research Societies or one of its adhering bodies. "Endorsed" identifies events endorsed by MRS.

▼ identifies a new or revised entry this month.

See the January 2004 MRS BULLETIN for March 2004 Calendar entries. For updates, access www.mrs.org/meetings/other/.

APRIL 2004

5–9 The Future of Materials Science and Engineering Education, *Kona, HI*. Paul Parisi, F. ASCE, e-mail pappe28@aol.com; www.engconfintl.org/4ap/html.

12–16 MRS Spring Meeting/ICEM 2004, *San Francisco, CA*. Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS/IUMRS.**

14–16 ▼ 2004 Intl. Conf. on Electronics Packaging and 18th Microelectronics Show, *Tokyo, Japan*. 2004 ICEP Secretariat, 3-12-2 Nishigokota, Suginami, Tokyo, Japan; 81-3-5310-2010; fax 81-3-5310-2011; e-mail ijep.or.jp; www.ijep.or.jp/icep.

18–21 106th ACerS Meeting, *Indianapolis, IN*. The American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 614-899-6109; e-mail info@acers.org; www.acers.org.

18–21 Optical Data Storage 2004, *Monterey, CA*. Optical Data Storage, www.spie.org/Conferences/Calls/04/ods/submitAbstract.

24–29 47th Annual Society of Vacuum Coaters Technical Conf., *Dallas, TX*. Carl Lampert, Star Science, 8730 Water Rd., Cotati, CA, 94931-4252; 707-794-0323; fax 707-794-0333; e-mail cm1star@juno.com; www.svc.org.

25–30 SPIE Int. Conf. on High-Power Laser Ablation, *Taos, NM*. Claude Phipps, Photonic Associates, Santa Fe, NM, www.spie.org.

26–27 ▼ NSF-Sponsored USACM Workshop on Computational Nanomechanics of Materials, *Chicago, IL*. Hanchen Huang, Rensselaer Polytechnic Inst., 110 8th Street, Troy, NY, 12180-3590; 518-276-2020; www.rpi.edu/~huangh/workshop.html.

26–28 MEMS IV—4th Annual ASME MEMS Technology Seminar, *Los Angeles, CA*. Jennifer Burns, ASME International, 3 Park Avenue, 23S1, New York, NY, 10016; 212-591-7423; fax 212-591-7143; e-mail burns@asme.org; www.asme.org/education/techsem/mems.

26–30 Photonics Europe: Showcasing the Age of Light, *Strasbourg, France*. Society of Photo-Optical Instrumentation Engineers, P.O. Box 10, Bellingham, WA, 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org/info/europe.

27–28 2004 Conf. on Ceramic Interconnect Technology, *Denver, CO*. Samuel Horowitz, DuPont Electronic and Communications Technology, e-mail samuel.j.horowitz@usa.dupont.com; www.imaps.org/ceramics.

MAY 2004

1–4 American Physical Society (APS) April 2004 Meeting, *Denver, CO*. Donna Baudrau, 301-209-3286; e-mail baudrau@aps.org; www.aps.org/meet/calendar.html.

5–7 ▼ Small Fuel Cells 2004, *Arlington, VA*. Serge Pan, Knowledge Foundation, 617-232-7400; fax 617-232-9171; e-mail custserv@knowledgefoundation.com; www.knowledgefoundation.com.

9–14 205th Meeting of the Electrochemical Society, *San Antonio, TX*. The Electrochemical Society, 65 S. Main St., Bldg. D, Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org/meetings/meetings.htm.

9–14 Advanced Short-Time Thermal Processing for Si-Based CMOS Devices II, *San Antonio, TX*. Fred Roozeboom, Philips Research Labs, WA14, Prof. Holstlaan 4, Eindhoven, The Netherlands, 31-40-2742767; fax 31-40-2743352; e-mail Fred.Roozeboom@philips.com; www.electrochem.org/meetings/future/205/meeting.html.

10–13 Quantum Dots Conf. 2004, *Banff, Alberta, Canada*. Sylvain Raymond, Inst. for Microstructural Science, 1200 Montreal Rd., Bldg M-23A, Ottawa, ON, Canada K1A 0R6; 613-990-9742; fax 613-952-8701; e-mail sylvain.raymond@nrc.ca; www.qd2004.com.

13–14 ▼ 5th Electronics Production and Packaging Technology Conf., *Pori, Finland*. IMAPS Nordic, www.pori.tut.fi/eltupak/indexengl.html.

16–19 Magneto-Optical Recording Intl. Sym. (MORIS 2004), *Yokohama, Japan*. MORIS 2004 Secretariat, Proactive Convention Co., Ltd., Eiko Bldg.2F, 93 Edomachi, Chuo-ku, Kobe 650-0033, Japan; 81-78-334-6661; fax 81-78-334-6662; e-mail moris2004@pac.ne.jp; www.pac.ne.jp/moris2004. **Endorsed.**

16–20 SAMPE 2004/Long Beach, *Long Beach, CA*. Doris Weaver, 626-331-0616 x 603; e-mail techprogram@sampe.org.

16–21 7th World Biomaterials Congress, *Sydney, Australia*. Biomaterials Congress Managers, GPO Box 128, Sydney NSW 2001, Australia; 61-2-9262-2277; fax 61-2-9262-3135; e-mail biomaterials@tourhosts.com.au; www.tourhosts.com.au/biomaterials.

16–21 ▼ 2004 Conf. on Lasers and Electro Optics/Intl. Quantum Electronics Conf. (2004 CLEO/IQEC), *San Francisco, CA*. 2004 CLEO/IQEC, 202-416-1907; e-mail cust.serv@osa.org; www.cleoconference.org.

18–20 IMAPS Int. High-Temperature Electronics Conf., *Santa Fe, NM*. Jackki Morris-Joyner, IMAPS, 305-382-8433; e-mail jmorriss@imaps.org; www.imaps.org.

23–28 Critical Materials Issues in Wide Bandgap Semiconductors, *Davos, Switzerland*. Subash Mahajan, Arizona State University, www.engconfintl.org/4ad.html.

23–28 ▼ Society for Information Display 2004 (SID 2004), *Seattle, WA*. SID 2004, e-mail conferences@sid.org; www.sid.org/conf/sid2004/sid2004.html.

24–26 ▼ Eighth World Congress on Biosensors, *Granada, Spain*. April Williams, Elsevier, The Boulevard, Langford Lane, Kidlington, Oxford, UK; 44-1865-843089; fax 44-1865-843-3958; e-mail a.williams@elsevier.com; www.biosensors-congress.com.

24–28 E-MRS Spring Meeting, *Strasbourg, France*. European Materials Research Society, 23 rue du Loess, B.P. 20, 67037 Strasbourg Cedex 02, France; 33-3-88-10-6372; 33-3-88-10-6293; e-mail emrs@phase.c-strasbourg.fr; www-emrs.c-strasbourg.fr. **E-MRS.**

26–28 Second SPIE Int. Symp. on Fluctuations and Noise, *Maspalomas, Spain*. Laszlo Kish, Texas A&M University, www.spie.org.

30–4 3rd Intl. Conf. on Computational Modeling and Simulation of Materials, *Acireale, Italy*. Technagroup, P.O. Box 174, Faenza, Italy; +0546-22461; fax +0546-664138; e-mail info@technagroup.it; www.technagroup.it/modeling.htm.

30–4 12th Int. Conf. on Metal-Organic Vapor Phase Epitaxy, *Lahaina, HI*. TMS Meetings Services, 184 Thorn Hill Road, Warrendale, PA, 15086; 724-776-9000; fax 724-776-3770; e-mail mtgserv@tms.org; www.tms.org.

JUNE 2004

1–4 ▼ 48th Intl. Conf. on Electron, Ion, and Photon Beam Technology and Nanofabrication, *San Diego, CA*. W. Meisburger, WD Meisburger Consulting, 1507 Montalban Drive, San Jose, CA, 95120; 408-396-3862; fax 408-997-1366; e-mail d.meisburger@att.net; www.eipbn.org.

7–8 European Coatings Conferences: Smart Coatings III, *Berlin, Germany*. Amanda Beyer, Vincentz Network, Schiffgraben 43, D-30175 Hannover, Germany; 49-511-99-10-271; fax 49-511-99-10-279; e-mail amanda.beyer@coatings.de; www.coatings.de.

7–11 Great Lakes Photonics Symp., *Cleveland, OH*. Pam Myers, 937-254-7950 ext. 1135; e-mail pmyers@anteon.com; www.usasymposium.com/glps.

9–10 ▼ Magnetism 2004: Advancements in Magnetic Applications, Technology and Materials, *Denver, CO*. Jeremy Martin, 720-528-3770 x118; e-mail jeremym@infowebcom.com; www.magnetismmagazine.com.

13–17 2004 Intl. Conf. on Powder Metallurgy & Particulate Materials, *Chicago, IL*. MPIF, 105 College Road East, Princeton, NJ, 08540; 609-452-7700; fax 609-987-8523; e-mail info@mpif.org; www.mpiif.org.

16–18 ▼ 3rd European Microelectronics and Packaging Symp., *Prague, Czech Republic*. Josef Sikula, Brno University of Technology, Technicka 8, 610 00 BRNO, Czech Republic; 00420-5-41143328; fax 00420-5-41143398; e-mail sikula@feec.vutbr.cz; www.imaps.cz/empas.

20–24 7th Int. Conf. on Nanostructured Materials (NANO 2004), *Wiesbaden, Germany*. Barbara Feibt, Theodor-Heuss-Allee 25, 60486 Frankfurt am Main, Germany, 49-69-7564-333; fax 49-69-7564-441; e-mail nano@nano2004.org; www.nano2004.org.

21–23 ▼ 62nd Annual Device Research Conf., *Notre Dame, IN*. TMS, TMS Meetings Services, 184 Thorn Hill Road, Warrendale, PA, 15086; 724-776-9000 x243; fax 724-776-3770; e-mail mtgserv@tms.org; www.tms.org/Meetings/Specialty/DRC/2004/DRC-2004-Home.html.

21–24 ▼ Topical Workshop & Exhibition on Flip Chip Technologies, *Austin, TX*. Ted Tessier, ST Assembly Test Services Inc., 9180 S. Kyrrene St., Suite 101, Tempe, AZ, 85284; 480-222-1735; e-mail tessiert@statsus.com; www.imaps.org.

21–25 2004 Natl. Space & Missile Materials Symp. (NSMMS), *Seattle, WA*. Dan Cleyrat, 937-656-6482; e-mail daniel.cleyrat@wpafb.af.mil; www.usasymposium.com.

23–25 ▼ 2004 TMS Electronic Materials Conf., *Notre Dame, IN*. April Brown, Duke University, 130 Hudson Hall, Durham, NC, 27708; 919-660-5442; fax 919-660-5293; e-mail abrown@ee.duke.edu; www.tms.org/EMC.html.

28–2 ▼ 7th Intl. Conf. on Computer Simulation of Radiation Effects in Solids (COSIRES 2004), *Helsinki, Finland*. Kai Nordlund, P.O. Box 43, 00014 Univ. of Helsinki, Helsinki, Finland; 358-9-19150007; e-mail knordlund@acclab.helsinki.fi; www.acclab.helsinki.fi/cosires2004.

28–4 ▼ 16th Intl. Vacuum Congress (IVC-16)/12th Intl. Conf. on Solid Surfaces (ICSS-12)/8th Intl. Conf. on Nanometer-Scale Science and Technology (NANO-8)/17th Vacuum National Symp. (AIV-17), *Venice, Italy*. Massimo Sancrotti, Istituto Nazionale, 39-040-3756-435; fax 39-040-226767; e-mail sancrotti@tasc.infm.it; www.ivc16.org.

JULY 2004

11-15 9th Intl. Conf. on the Structure of Non-Crystalline Materials, *Corning and Alfred, NY*. A.N. Cormack, New York State College of Ceramics at Alfred Univ., 2 Pine St., Alfred, NY 14802; 607-871-2980; e-mail cormack@alfred.edu; nyscc.alfred.edu/NCM9.

19-23 Intl. Workshop on Nitride Semiconductors, *IWN04, Pittsburgh, PA*. Materials Research Society, Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS.**

20-26 31st Workshop of the Intl. School of Solid State Physics, *Erice, Italy*. Andrea Rapisarda, Catania, Italy; 39-095-378-5408; fax 39-095-378-5231; e-mail andrea.rapisarda@ct.infn.it; www.ct.infn.it/~rapis/ERICE-COMPLEX04.

21-23 Third Int. Workshop on the Physics and Applications of Spin-Related Phenomena in Semiconductors, *Santa Barbara, CA*. D. Awschalom, University of California, Santa Barbara, CA, 93106-9530; 805-893-2121; e-mail awsch@physics.ucsb.edu.

21-25 Int. Conf. on Superlattices, Nanostructures & Nanodevices (ICSNN-04), *Cancun, Mexico*. P. Pereyra, Universidad Autonoma Metro., Av. S. Pablo, 180, Col. Reynosa, Mexico D.F., Mexico; (52-55) 5318-9359; fax (52-55) 5318-9540.

22-25 European Conf. on Organized Films (ECOF 2004), *Valladolid, Spain*. E-mail souto@fmc.uva.es.

26-30 Int. Conf. on the Physics of Semiconductors, *Flagstaff, AZ*. Stefan Zollner, Motorola, Inc., 2100 E. Elliot Rd., Tempe, AZ, 85284; 480-413-2817; fax 480-413-2680; www.icps2004.org. **Endorsed.**

AUGUST 2004

1-6 Gordon Research Conf. on High-Temperature Materials, Processes and Diagnostics, *Waterville, ME*. Klaus Hilpert, Research Center Jülich, Jülich, Germany, 49-2461-61-3280; fax 49-2461-61-3699; e-mail k.hilpert@fz-juelich.de. **Endorsed.**

2-5 11th Int. Conf. on High Magnetic Fields in Semiconductor, *Berkeley, CA*. P. Yu, University of California, Berkeley, CA, 94720; 510-642-8087; fax 510-643-8497; e-mail ppyu@lbl.gov.

2-6 16th Int. Conf. on High Magnetic Fields in Semiconductor Physics, *Tallahassee, FL*. Y.-J. Wang, 850-644-1496; fax 850-644-0534; e-mail wang@magnet.fsu.edu; www.semimag16.magnet.fsu.edu.

2-6 49th Annual SPIE Meeting, and Intl. Symp. on Optical Science and Technology, *Denver, CO*. SPIE, SPIE Meetings, P.O. Box 10, Bellingham, WA, 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; spie.org/info/am.

9-13 14th Intl. Conf. on Crystal Growth (ICCG-14)/12th Intl. Conf. on Vapor Growth and Epitaxy (ICVGE-12), *Grenoble, France*. Fabien Briola, 33-491-462556; e-mail iccg14exhibitors@atout-org.com; iccg14.inpg.fr.

22-25 COM2004: The Conf. of Metallurgists, *Hamilton, ON*. Ken Coley, McMaster Steel Research Centre, Hamilton, ON, L8S 4L7; 905-525-9140; fax 905-526-8404; e-mail coleyk@mcmaster.ca; www.metsoc.org.

22-26 XIII Intl. Materials Research Congress, *Cancun, Mexico*. Col. Ladrillera de Benitez, 52-222-211-4393; fax 52-222-211-4394; www.viep.buap.mx/imrc2004.htm.

23-25 4th Conf. on Synchrotron Radiation in Materials Science, *Grenoble, France*. Fabienne Mengoni, e-mail srms-4@esrf.fr; www.esrf.fr/Conferences/SRMS-4.

23-27 3rd Intl. Conf. on HWCVD (Cat-CVD) Process, *Utrecht, Netherlands*. Ruud Schropp, Utrecht University, Debye Inst, Princetonplein 5, Utrecht, The Netherlands; 31-30-253-3170; fax 31-30-254-3165; e-mail R.E.I.Schropp@phys.uu.nl; www.hwcvd.nl.

23-27 9th Int. Conf. on Ferrites, *San Francisco, CA*. Alex Goldman, Ferrite Technology Worldwide, 4625 Fifth Ave. #305, Pittsburgh, PA, 15213; e-mail ferritetec@aol.com; www.ceramics.org/meetings/ferrites/default.asp.

23-27 2004 IEEE Intl. Ultrasonics, Ferroelectrics, and Frequency Control 50th Anniversary Joint Conf., *Montreal, Canada*. R. Michael Garvey, Symmetricom, 34 Tozer Road, Beverly, MA; 01915-5510; 978-232-1417; fax 978-927-4099; e-mail rmgarvey@symmetricom.com; www.ieee-uffc.org.

25-27 ASM Materials & Processes for Medical Devices Conf., *St. Paul, MN*. ASM International, Materials Park, OH, 44073-0002; 440-338-5151; fax 440-338-4634; www.asminternational.org/meddevices.

SEPTEMBER 2004

1-2 RP Asia 2004—Promoting the Growth of Composites in Asia, *Bangkok, Thailand*. Nick Williams, 44-1743-241-289; fax 44-870-138-9539; www.rpasia.com.

5-10 Intl. Conf. on Polycrystalline Semiconductors—POLYSE 2004, *Potsdam, Germany*. Norbert Nickel, Hahn-Meitner-Institut Berlin, Kekulestr. 5, Berlin, Germany; 49-30-67053-301; fax 49-30-67053-333; e-mail nickel@hmi.de.

5-10 Joint European Magnetic Symposia - JEMS 2004, *Dresden, Germany*. Anke Kirchner, IFW Dresden, P.O. Box 27 00 16, Dresden, Germany, 49-351-465-9405; fax 45-351-465-9541; e-mail jems04@ifw-dresden.de; www.ifw-dresden.de/imw/jems04.

6-9 Junior Euromat 2004, *Lausanne, Switzerland*. Anja Mangold, Hamburger Allee 26, D-60486, Frankfurt, Germany; 49-69-7917-747; fax 49-69-7917-733; e-mail junior-euromat@fems.org; www.junior-euromat.fems.org.

6-10 E-MRS Fall 2004 Meeting, *Warsaw, Poland*. E-MRS Fall 04, e-mail fall2004@e-mrs.org; www.e-mrs.org/meetings/fall2004. **E-MRS.**

12-16 5th Intl. Conf. on High Temperature Ceramic Matrix Composites, *Seattle, WA*. The American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 614-899-6109; e-mail info@acers.org; www.acers.org.

13-17 Nano & Giga Challenges in Microelectronics (NGCM 2004), *St. Petersburg, Russian Federation*. Anatoli Korkin, 480-539-4754; e-mail korkin@nanoandgiga.com; www.asdn.net/ngcm2004. **Endorsed.**

13-17 Ninth Int. Conf. on Plasma Surface Engineering, *Garmisch-Partenkirchen, Germany*. Karin Reichel, VDI-Technology Center, Graf-Recke-Str. 84, D-40239, Duesseldorf, Germany; 49-211-6214-640; fax 49211-6214-575-484; e-mail akplasma@vdi.de; www.akplasma.org/pse2004.php3.

19-21 Fourth Intl. Conf. on Inorganic Materials, *Antwerp, Belgium*. Phillipa Fletcher, Gregor, Winter Lane, West Hanney, Nr Wantage, Oxon, United Kingdom; 44-1235-868811; fax 44-1235-868811; e-mail phillipa.fletcher@diaf.pipex.com; www.im-conference.com/contact.htm.

19-23 2nd Intl. Conf. on Environment-Induced Cracking of Metals (EICM-2), *Banff, Alberta, Canada*. Sergei Shipilov, Banff, AB, 403-220-4149; fax 403-282-8406; e-mail shipilov@enme.ucalgary.ca; www.enme.ucalgary.ca/EICM-2.

19-23 10th Intl. Symp. on Superalloys, *Champion, PA*. TMS Meeting Services, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail mtgserv@tms.org; www.tms.org/Meetings/Specialty/Superalloys2004/SuperalloysHome.html.

20-21 Potentials and Risks of Nanoscale Materials, *Augsburg, Germany*. Bernd Stritzker, Universität Augsburg, Lehrstuhl Experimentalphysik 4, Institut für Physik, D-86135 Augsburg, Germany; 49-821-598-3400; fax 49-821-598-3425; e-mail stritzker@physik.uni-augsburg.de. **Endorsed.**

20-25 13th Semiconducting and Insulating Materials Conference (SIMC-XIII-2004), *Beijing, Peoples Republic of China*. Yonghai Chen, Chinese Academy of Sciences, P.O. Box 912, Beijing 100083, Peoples Republic of China; 86-10-8230-4227; fax 86-10-8230-5052; e-mail yhchen@red.semi.ac.cn.

21-24 Intl. Conf. on Semi Solid Processing of Alloys and Composites, *S2P 2004, Limassol, Cyprus*. Carol Garofoli, Worcester Polytechnic Institute, 100 Institute Road, Worcester, MA, 01609-2280; 1-508-831-5592; fax 1-508-831-5993; e-mail s2p@wpi.edu; www.wpi.edu/News/Conf/S2P.

OCTOBER 2004

3-8 206th Meeting of the Electrochemical Society, *Honolulu, HI*. The Electrochemical Society, 65 S. Main St., Bldg. D, Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org/meetings/meetings.htm.

3-8 Applied Superconductivity Conf. (ASC/04), *Jacksonville, FL*. ASC 2004, www.ascinc.org.

4-7 23rd Intl. Conf. on Applications of Lasers & Electro-Optics (ICALEO 2004), *San Francisco, CA*. LIA Conf. Dept., e-mail conferences@laserinstitute.org; www.icaleo.org.

6-8 7th Intl. and Interdisciplinary Symp. of the Working Group on "Biomaterials and Tissue Compatibility," *Essen, Germany*. Universität Duisburg-Essen, Alfons Fischer, Werkstofftechnik II, Lotharstr. 1, 47057 Duisburg, Germany; 49-203-379-4373; fax 49-203-379-4374; e-mail wtechi@uni-duisburg.de.

7-8 14th Intl. Activated Carbon Conf., *Pittsburgh, PA*. Henry Nowicki, e-mail hnpacs@aol.com; members.aol.com/hnpacs/conferences/IACCI4.htm

10-14 Frontiers in Optics 2004, *Rochester, NY*. Robert Boyd, University of Rochester, Rochester, NY, www.frontiersinoptics.org.

17-24 PM2004 Powder Metallurgy World Congress and Exhibition, *Vienna, Austria*. EPMA, Old Bank Buildings, Bellstone, Shrewsbury, United Kingdom, 44-1743-248899; fax 44-0-1743-362968; e-mail fh@epma.com; www.epma.com/pm_2004/technical_program.htm.

19-21 Advanced Metallization Conf. (AMC) 2004, *San Diego, CA*. 510-642-8087; fax 510-642-6027; e-mail amc@unex.berkeley.edu.

NOVEMBER 2004

7-11 2004 AAPS Annual Meeting and Exposition, *Baltimore, MD*. AAPS, www.aapspharmaceutica.com/meetings/index.asp.

7-12 Glass and Optical Materials Division Fall Meeting co-located with the Intl. Symp. on Non-Oxide Glasses, *Cocoa Beach, FL*. John Ballato, Clemson University, 864-646-4852; e-mail john.ballato@ces.clemson.edu; www.ceramics.org/meetings/glass2004/default.asp

14-16 37th IMAPS Annual Symposium on Microelectronics, *Long Beach, CA*. IMAPS, 611 2nd St., N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

15-18 36th Intl. SAMPE Technical Conf., *San Diego, CA*. DeWayne Howell, CompositeTek, Boulder, CO, 303-530-2919; fax 303-530-9437; e-mail dhowell@compositetek.com; www.sampe.org.

15-19 51st AVS Intl. Symposium, *Anaheim, CA*. American Vacuum Society, 120 Wall St., 32nd Floor, New York, NY 10005; 212-248-0200; fax 212-248-0245; e-mail avsnyc@avs.org; www.avs.org.

15-19 ASNT Fall Conf. & Quality Testing Show 2004, *Las Vegas, NV*. Kelly Wise, 1-614-274-6003; fax 1-614-274-6899; e-mail kwise@asnt.org; www.asnt.org/events/conferences/fc04/prospectus.pdf.

24-26 ▼ 1st Intl. Symp. on Shape Memory and Related Technologies (SMART 2004), Singapore. Yong Liu, Nanyang Technological Univ., Nanyang Ave., Singapore; 65-6790-4951; e-mail mliuy@ntu.edu.sg; www.ntu.edu.sg/home/mliuy/SMA RT2004.htm.

29-3 **MRS Fall Meeting, Boston, MA.** Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS.**

DECEMBER 2004

6-8 Intl. Symp. on Advanced Materials and Processing, Kharagpur, India. A.K. Banthia, Indian Institute of Technology, Kharagpur, India, 91-3222-282274; e-mail akb@matssc.iitkgp.ernet.in; www.iitkgp.ernet.in/departments/home.php?deptcode=MS.

JANUARY 2005

10-14 ▼ IUVSTA Workshop on One-Dimensional Nanomaterials, Taipei, Taiwan. R. Chu-Chen, 886-2-33665202; fax 886-2-23655404; e-mail iuvsta@ms.ntu-ccms.ntu.edu.tw.

FEBRUARY 2005

6-11 ▼ Second Intl. Conf. on Advanced Materials and Nanotechnology (AMN-2), Queenstown, New Zealand. Conference Secretariat, University of Canterbury, Private Bag 4800, Christchurch, New Zealand; 64-3-364-2534; fax 64-4-364-2324; e-mail amn2@cont.canterbury.ac.nz; www.macdiarmid.ac.nz/amn-2.

MARCH 2005

14-18 ▼ ASNT Spring Conf. and 14th Annual Research Symp., Albuquerque, NM. Kelly Wise, 614-274-6003; fax 614-274-6899; e-mail kwise@asnt.org.

APRIL 2005

4-8 ▼ 2005 Intl. Magnetics Conf. (INTERMAG2005), Nagoya, Japan. Intermag 2005 Secretariat, c/o Convention Linkage, Inc., Akasaka-Nihon Bldg., 9-5-24, Akasaka, Minato-ku, Tokyo 107-0052, Japan; 81-3-5770-5531; fax 81-3-5770-5532; e-mail info@intermag2005.jp; www.intermag2005.jp. **Endorsed.**

11-14 ▼ Microscopy of Semiconducting Materials, Oxford, United Kingdom. MSM 2005, Royal Microscopical Society, 37/38 St Clemens, Oxford, UK OX4 1AJ; 44-1865-248768; e-mail info@rms.org.uk.

JULY 2005

3-8 ▼ Intl. Conf. on Materials for Advanced Technologies (ICMAT 2005) and IUMRS-ICAM 2005, Singapore. Mat Research Soc (Singapore), ICMAT Secretariat, 3 Research Link, Singapore, Singapore, 65-6874-1975; fax 65-6777-2393; e-mail icmat@mrs.org.sg; www.mrs.org.sg/meeting_future.html. **IUMRS/MRS-S.**

17-22 ▼ Intl. Conf. on Solid State Ionics (SSI-15), Baden-Baden, Germany. Ellen Ivers-Tiffée, c/o Universität Karlsruhe, Kaiserstr. 12, D-76131 Karlsruhe, Germany; 49-721-608-7491; fax 49-721-608-7492; e-mail info@ssi-15.net; www.ssi-15.net.

AUGUST 2005

28-2 ▼ 6th Intl. Conf. on Nitride Semiconductors (ICNS-6), Bremen, Germany. Sven Einfeldt, University of Bremen, P.O. Box 330440, Bremen, Germany; 49-421-218-7453; fax 49-421-218-4581; e-mail icns6@ifp.uni-bremen.de; www.ifp.uni-bremen.de/icns6.

OCTOBER 2005

17-21 ▼ ASNT Fall Conf. and Quality Testing Show 2005, Columbus, OH. Kelly Wise, 1-614-274-6003; fax 1-614-274-6899; e-mail kwise@asnt.org. □

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